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## Semiconductor devices –

### Part 16-4: Microwave integrated circuits Switches

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International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland  
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: [inmail@iec.ch](mailto:inmail@iec.ch) Web: [www.iec.ch](http://www.iec.ch)



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## CONTENTS

FOREWORD.....	3
1 Scope .....	5
2 Normative references .....	5
3 Terms and definitions .....	5
4 Essential ratings and characteristics .....	7
4.1 Circuit identification and types .....	7
4.2 Application description.....	8
4.3 Specification of the function .....	8
4.4 Limiting values (absolute maximum rating system) .....	10
4.5 Operating conditions (within the specified operating temperature range) .....	11
4.6 Electrical characteristics .....	11
4.7 Mechanical and environmental ratings, characteristics and data .....	12
4.8 Additional information .....	12
5 Measuring methods .....	13
5.1 General.....	13
5.2 Insertion loss ( $L_{ins}$ ) .....	14
5.3 Isolation ( $L_{iso}$ ) .....	16
5.4 Return loss ( $L_{ret}$ ) .....	18
5.5 Input power at 1 dB compression ( $P_{i(1dB)}$ ) and output power at 1 dB compression ( $P_{o(1dB)}$ ) .....	20
5.6 Turn-on time ( $t_{on}$ ), turn-off time ( $t_{off}$ ), rise time ( $t_{r(out)}$ ), and fall time ( $t_{f(out)}$ ).....	21
5.7 Adjacent channel power ratio ( $P_{o(mod)}/P_{ac}$ ) .....	23
5.8 n-th order harmonic distortion ratio ( $P_{nth}/P_1$ ).....	26
 Bibliography .....	 28
 Figure 1 – Circuit diagram for the measurement of the insertion loss $L_{ins}$ .....	 14
Figure 2 – Circuit diagram for the measurement of the isolation $L_{iso}$ .....	16
Figure 3 – Circuit for the measurements of the return loss .....	18
Figure 4 – Circuit for the measurements of switching time.....	21
Figure 5 – Input and output waveforms.....	21
Figure 6 – Circuit for the measurement of the adjacent channel power ratio .....	23
Figure 7 – Circuit diagram for the n-th order harmonic distortion ratio .....	26

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## SEMICONDUCTOR DEVICES –

Part 16-4: Microwave integrated circuits –  
Switches

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The text of this standard is based on the following documents:

FDIS	Report on voting
47E/256/FDIS	47E/261/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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## SEMICONDUCTOR DEVICES –

### Part 16-4: Microwave integrated circuits – Switches

#### 1 Scope

This part of IEC 60747 provides new measuring methods, terminology and letter symbols, as well as essential ratings and characteristics for integrated circuit microwave switches.

There are many combinations for RF ports in switches, such as SPST (single pole single throw), SPDT (single pole double throw), SP3T (single pole triple throw), DPDT (double pole double throw), etc. Switches in this standard are based on SPDT. However, this standard is applicable to the other types of switches.

#### 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60617-12, *Graphical symbols for diagrams – Part 12: Binary logic elements*

IEC 60617-13, *Graphical symbols for diagrams – Part 13: Analogue elements*

IEC 60747-1(1983), *Semiconductor devices – Discrete devices and integrated circuits – Part 1: General*  
Amendment 3 (1996)

IEC 60747-4, *Semiconductor devices – Discrete devices – Part 4: Microwave devices*

IEC 60748-2, *Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits*

IEC 60748-3, *Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits*

IEC 60748-4, *Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits*